

1 ABSTRACT OF THE DISCLOSURE

2 A semiconductor processor for spray coating wafers or other  
3 semiconductor articles. The processor has a compartment in which are  
4 mounted a wafer transfer, coating station and thermal treatment station.  
5 The coating station has a spray processing vessel in which a movable  
6 spray-head and rotatable wafer holder. The spray station has coating  
7 viscosity control features. An ultrasonic resonating spray-head is  
8 precisely supplied with coating from a metering pump. The heat  
9 treatment station heat cures the coating and then cools the wafer. The  
10 system allows coatings to be applied in relatively uniform conformational  
11 layers upon irregular surfaces.  
12  
13  
14  
15  
16  
17  
18  
19  
20  
21  
22  
23  
24